

16562 U.S. PTO
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22278 U.S. PTO
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022304

EXPRESS MAIL LABEL NO. ER 003068951 US
Date of Deposit 2/23/04
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Appn. Ser. No Not Yet Ass'd : Art Unit Not Yet Ass'd
Filed Herewith : Examiner Not Yet Ass'd
Inventors L.S. Mokl : Atty. Dkt. No. YOR920030206US1

For: HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR CHIP STRUCTURES

PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 - 1450
Sir:

Transmitted herewith for filing is a Patent Application including:

Request and Transmittal Letter - 1 page
Patent Specification, Claims & Abstract - 12 pages
Informal Drawings - 6 sheets
Declaration - 3 pages
Assignment + cover - 3 pages
Deposit Acct. Authorizations for Filing Fee and for As'mt recordation fee.
Information Disclosure Transmittal plus references

The filing fee has been calculated as shown below:

Basic Fee	\$770.00
Total claims 9 - 20 = 0 extra	00.00
Independent claims 2 - 3 = 0 extra	00.00
Filing fee Total	\$770.00

The assignment recordation fee of \$40.00

Deposit account authorizations for \$770.00 and \$ 40.00 are included

Respectfully submitted,

by *Alvin J. Riddles* 2/23/04

Alvin J. Riddles
Reg. No. 17862

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Inventors L. S. Mok : Atty. Dkt. No. YOR920030206US1

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EXPRESS MAIL CERTIFICATE

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 – 1450
Sir:

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Date of Deposit 02/23/04

I hereby certify that the following attached paper or fee

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Declaration – 3 pages

Assignment + cover–3 pages

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by

Alvin J. Riddles

Typed or Printed Name of person mailing paper or fee

Alvin J. Riddles 2/23/04

Signature and date of person mailing paper or fee

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Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 - 1450
Sir:

DEPOSIT ACCOUNT CHARGE AUTHORIZATION LETTER

For the Filing Fee for the above identified application
a charge authorization estimated to be \$770.00 on Deposit Account 50-0510 is provided
herewith.

Respectfully submitted,

by  2/23/04

Alvin J. Riddles
Reg.No. 17862

Dkt. No. YOR920030206US1

EXPRESS MAIL LABEL NO. ER 003068951 US
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In Re Appn. Ser. No Not Yet Ass'd : Art Unit Not Yet Ass'd
Filed Herewith : Examiner Not Yet Ass'd
Inventors L.S. Mokl : Atty. Dkt. No. YOR920030206US1


For: HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR CHIP STRUCTURES

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 – 1450
Sir:

DEPOSIT ACCOUNT CHARGE AUTHORIZATION LETTER

For the Assignment Recordation Fee for the above identified application a charge authorization of \$ 40.00 on Deposit Account 50-0510 is provided herewith.

Respectfully submitted,

by  2/23/04
Alvin J. Riddles
Reg.No. 17862

Dkt. No. YOR920030206US1